

/ Descriptions

TO-220 PNP Silicon PNP transistor in a TO-220 Plastic Package.

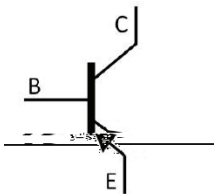
/ Features

 , 2SC2654
Large current capacity with small package, low collector saturation voltage, pair with 2SC2654.

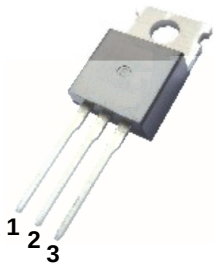
/ Applications

For low-frequency power amplifiers and mid-speed switching.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

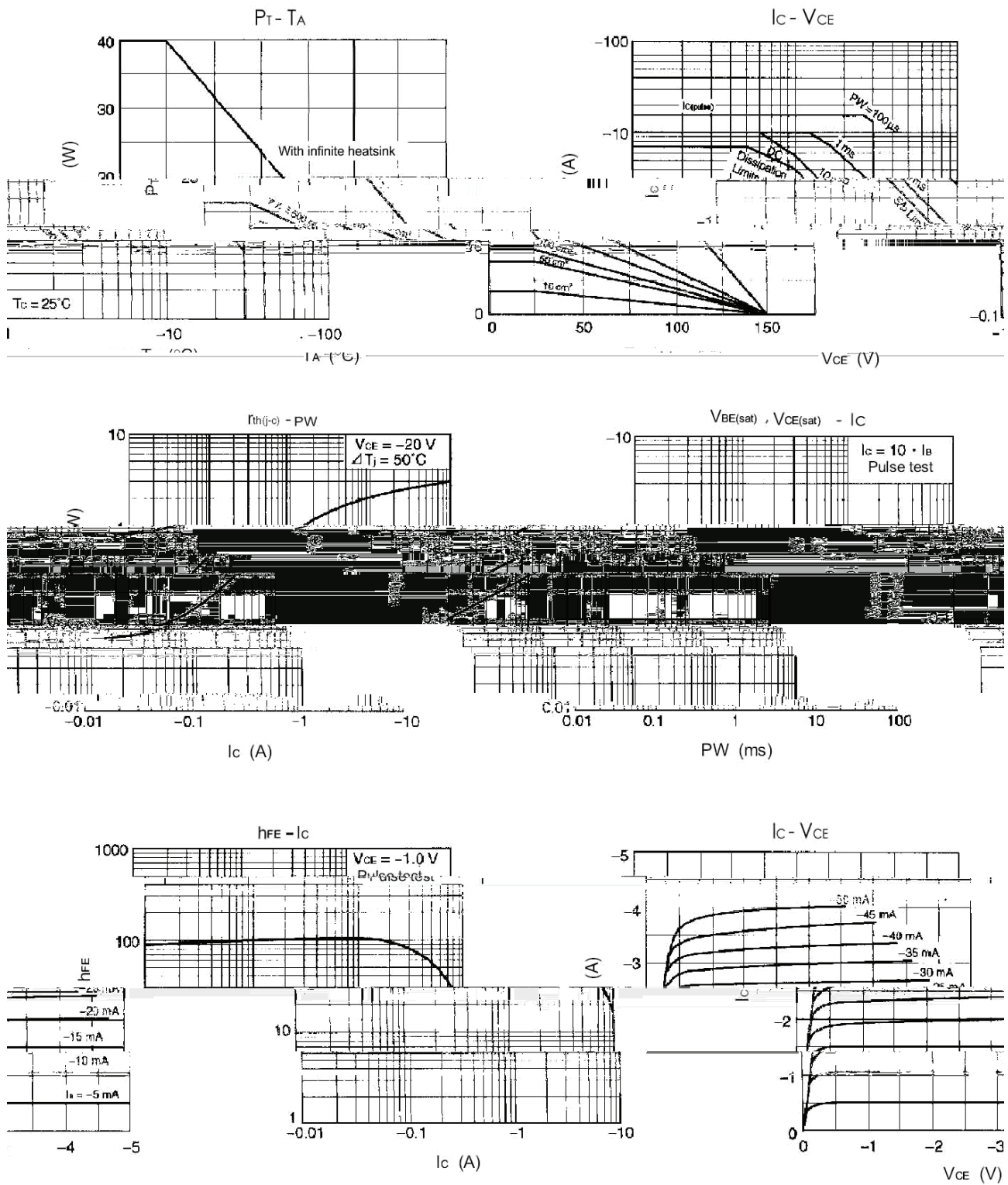
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	M	L	K	J
h_{FE} Range	40 80	60 120	100 200	160 320

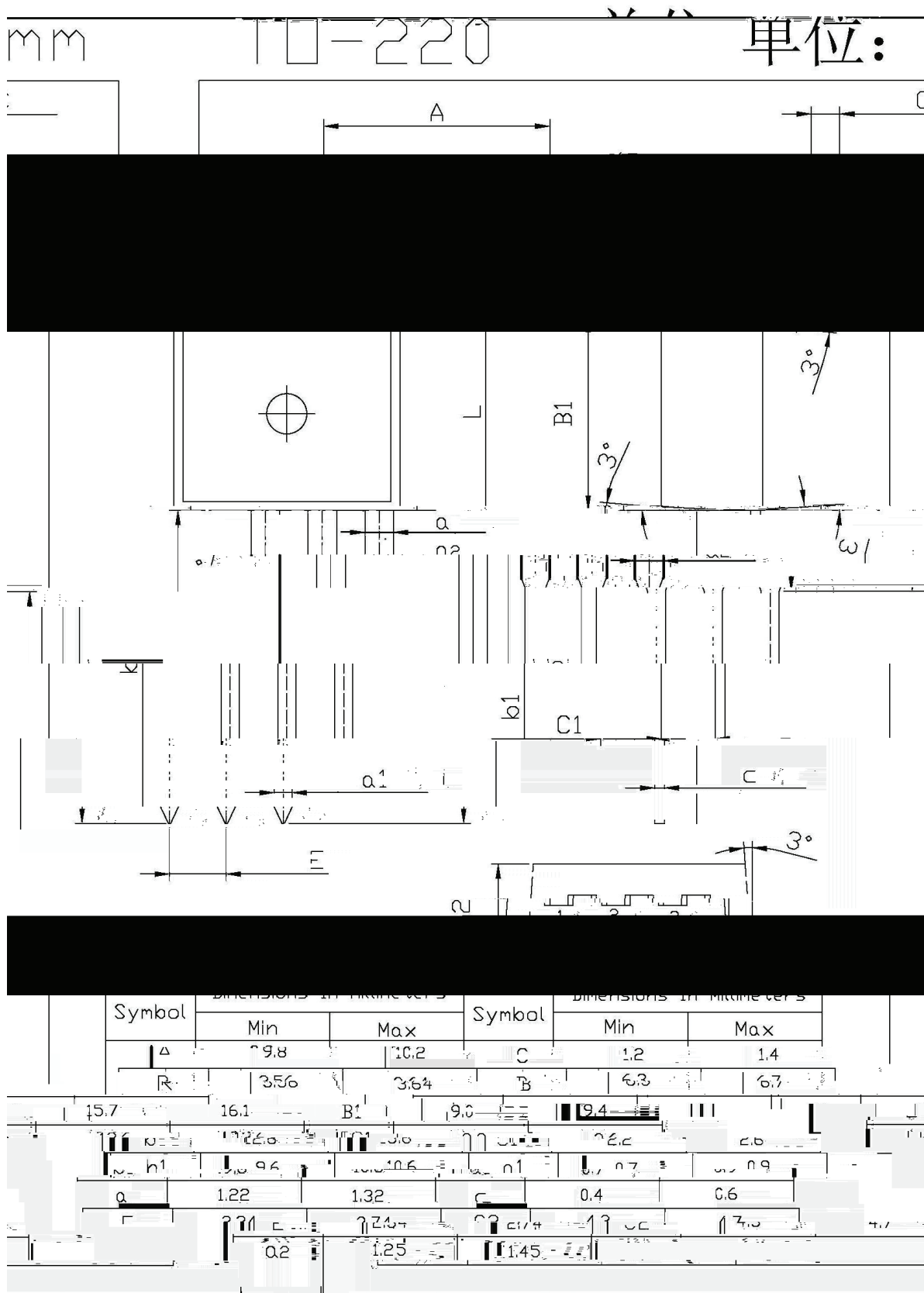
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-100	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-7.0	V
Collector Current - Continuous	I_C	-7.0	A
Collector Current – Continuous(Pulse)	I_{CP}	-15	A
Base Current - Continuous	I_B	-3.5	A
Collector Power Dissipation	$P_C(T_C=25^{\circ}C)$	40	W
	P_C	1.5	W
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature Range	T_{stg}	-55 150	$^{\circ}C$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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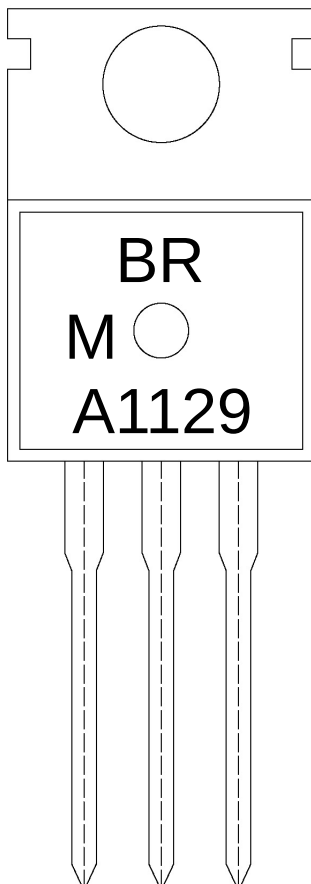
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

A1129

M: h_{FE}

Note:

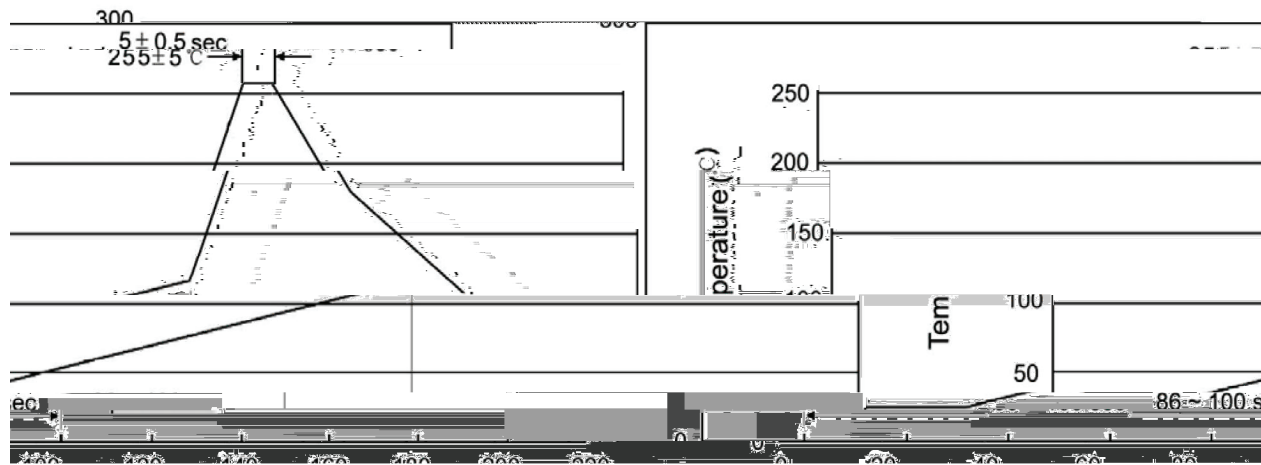
BR: Company Code

A1129: Product Type.

M: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:255±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5℃ Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

/ TUBE

Package Type

封装形式

Units 包装数量

Dimension 包装尺寸

(unit: mm